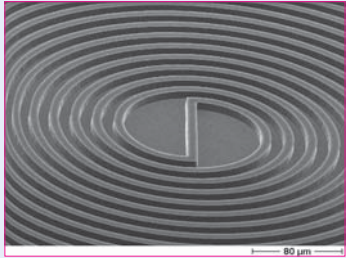


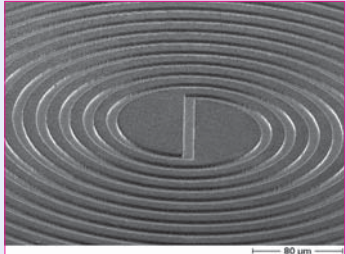
ma-P 1275 — Positive Tone Photoresist

Ultra Thick Resist for UV Lithography

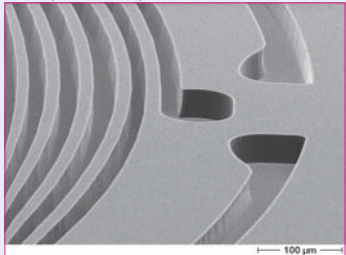
Resist patterning with mask aligner, broadband exposure



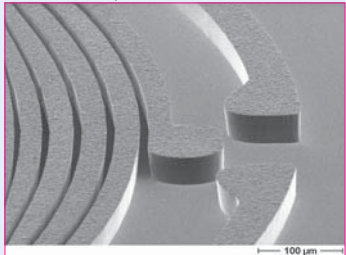
ma-P 1275, 7.5 µm thickness



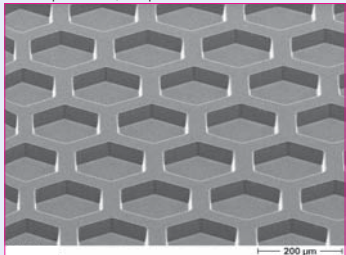
Electroplated Ni, 5 µm thickness



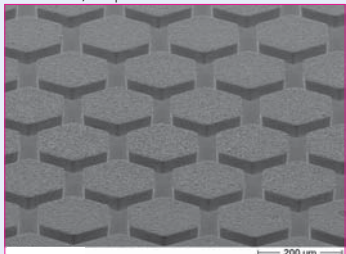
ma-P 1275, 30 µm thickness



Electroplated Ni, 28 µm thickness



ma-P 1275, 40 µm thickness



Electroplated Ni, 38 µm thickness

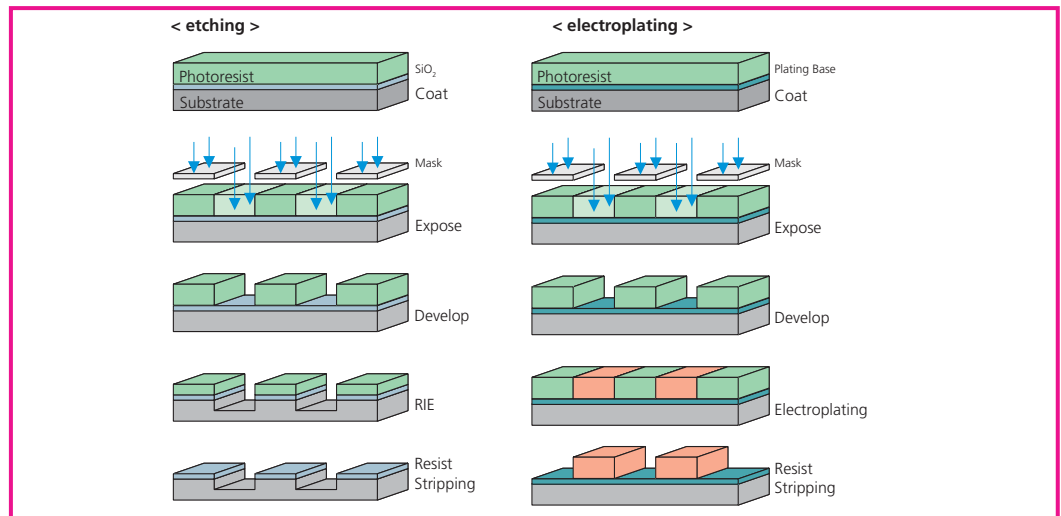
Unique features

- Outstanding pattern stability in wet etch processes and acid and alkaline plating baths from pH 1 - 13.5
- Highly stable in dry etch processes e.g. CHF_3 , CF_4 , SF_6
- Aqueous alkaline development
- Easy to remove
- Side wall angle up to 84°

Applications

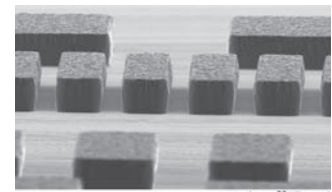
- Moulds for electroplating, e.g.
 - Micro optical components
 - Micro springs
 - Bumping
- Mask for etching e.g.
 - Si, SiO_2
 - Metals
 - Semiconductors
- Mask for ion implantation

Process flow



Technical data

Film thickness	µm	7.5	20	30	40
Spin coating	rpm	3000	500	350	250
Spin time	s	30	90	90	90
Aspect ratio		3 - 4	3 - 4	3 - 4	3 - 4



Cuboid Ni structures, 17 µm thickness

